

## 1200V 40mΩ N-Channel SiC Power MOSFET

### Description

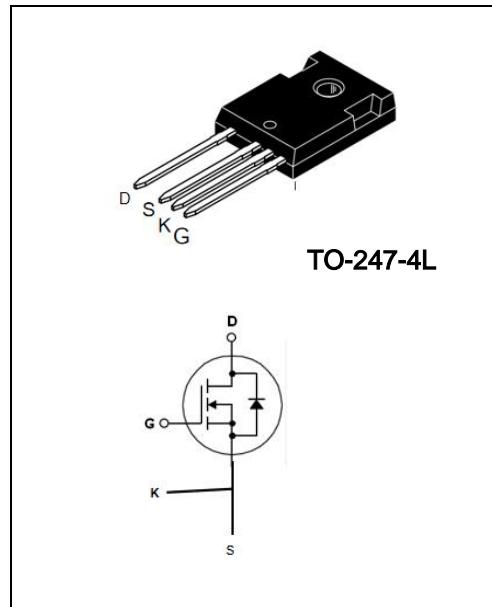
The AKCT40N120H4L is a high blocking voltage N-Channel SiC power MOSFET. This device provide excellent performance for high voltage power supplies or pulse circuits.

### Features

- Typical on-Resistance:  $R_{DS(on)}=40\text{m}\Omega(\text{typ.})$
- High Blocking Voltage
- 100% Avalanche Test
- Good Stability and Uniformity with High  $E_{AS}$

### Applications

- Solar Inverters
- High Voltage DC/DC Converters
- Motor Drivers
- Switch Mode Power Supplies



### Absolute Maximum Ratings @ $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Unit	
$V_{DSS}$	Drain to Source Voltage	1200	V	
$V_{GSS}$	Gate to Source Voltage	-10/+25	V	
$V_{GSop}$	Recommended operation Values of Gate -Source Voltage	-5/+20	V	
$I_D$	Drain Current	$T_c=25^\circ\text{C}$	61	A
		$T_c=100^\circ\text{C}$	42	A
$I_{DM}$	Pulsed Drain Current (Note1)	120	A	
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	250	W
	Derate above 25°C		1.67	W/°C
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	300	mJ	
$T_J$	Operating Junction Temperature Range	-50~+175	°C	
$T_{STG}$	Storage Temperature Range	-50~+175	°C	

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{th(J-C)}$	Thermal Resistance, Junction to case	0.6	°C/W
$R_{th(J-A)}$	Thermal Resistance, Junction to Ambient	40	°C/W

**Electrical Characteristics @ $T_C=25^\circ\text{C}$  unless otherwise noted**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain to Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=2\text{mA}$	1200	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=5\text{mA}$	2.0	2.5	4.0	V
$R_{\text{DS(on)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=20\text{V}, I_{\text{D}}=20\text{A}$	-	44	65	$\text{m}\Omega$
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=V_{\text{DSS}}, V_{\text{GS}}=0\text{V}$	-	-	100	$\mu\text{A}$
$I_{\text{GSS}}$	Gate to Source Leakage Current	$V_{\text{GS}}=V_{\text{GSS}}, V_{\text{DS}}=0\text{V}$	-	-	$\pm 500$	nA

**D-S Diode Characteristics and Maximum Rating @ $T_C=25^\circ\text{C}$  unless otherwise noted**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$V_{\text{SD}}$	Drain-Source Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=40\text{A}$	-	3.9	-	V
$t_{\text{rr}}$	Reverse Recovery Time	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=40\text{A}, \frac{dI}{dt}=-290\text{A}/\text{us}$	-	30	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge		-	590	-	nC

**Switching Characteristics @ $T_C=25^\circ\text{C}$  unless otherwise noted**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on Delay Time	$I_{\text{D}}=40\text{A}, V_{\text{DD}}=800\text{V}, R_{\text{G}}=2.5\Omega, V_{\text{GS}}=-5/20\text{V}, (\text{Note 3})$	-	12	-	ns
$t_r$	Turn-on Rise Time		-	12	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	23	-	ns
$t_f$	Turn-off Fall Time		-	6.7	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=1000\text{V}, f=1.0\text{MHz}$	-	2946	-	pF
$C_{\text{oss}}$	Output Capacitance		-	167	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	6.6	-	pF
$Q_g$	Total Gate Charge	$I_{\text{D}}=40\text{A}, V_{\text{DD}}=800\text{V}, V_{\text{GS}}=-5/20\text{V}, (\text{Note 3})$	-	142	-	nC
$Q_{\text{ge}}$	Gate to Source Charge		-	37	-	nC
$Q_{\text{gd}}$	Gate to Drain Charge		-	18	-	nC

**Note:**

1. Repetitive rating: pulse-width limited by maximum junction temperature
2.  $V_{\text{DD}}=100\text{V}, L=10\text{mH}, V_{\text{clamp}}=1600\text{V}, V_{\text{G}}=10\text{V}, I_{\text{D}}=19.0\text{A}$
3. Essentially independent of operating temperature typical characteristics

## Typical Performance Characteristics

Fig. 1. Typical on-Resistance Characteristics

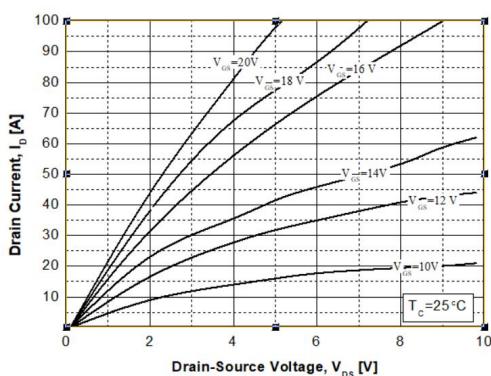


Fig. 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

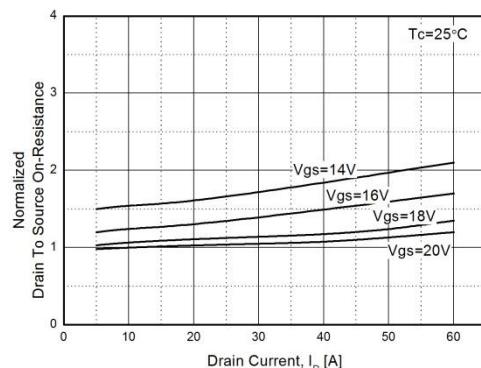


Fig. 3. Normalized On-Resistance vs. Junction Temperature

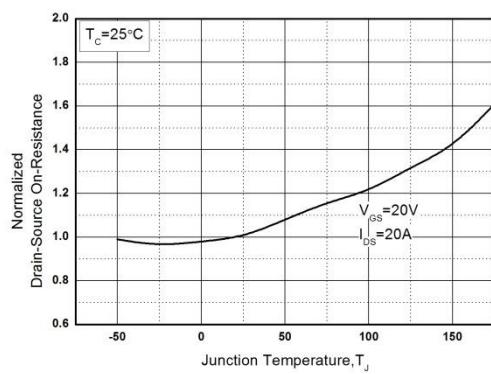


Fig. 4. On-Resistance vs. Gate-to-source Voltage

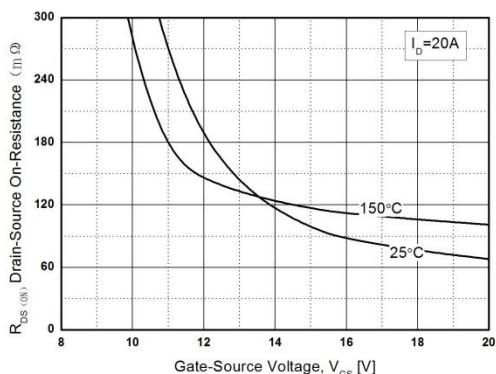


Fig. 5. Transfer Characteristics

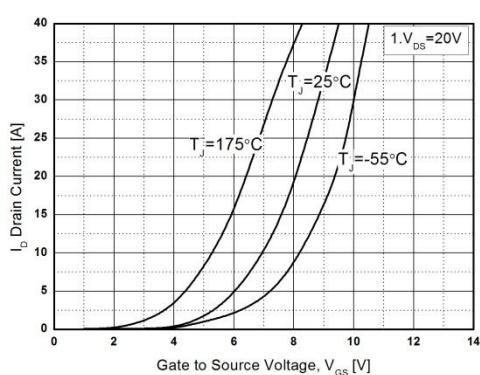
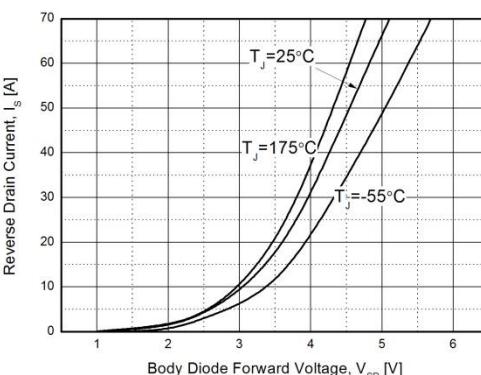


Fig. 6. Source-to-Drain Diode Forward Voltage vs. Source Current



## Typical Performance Characteristics

Fig. 7. Gate Charge Characteristics

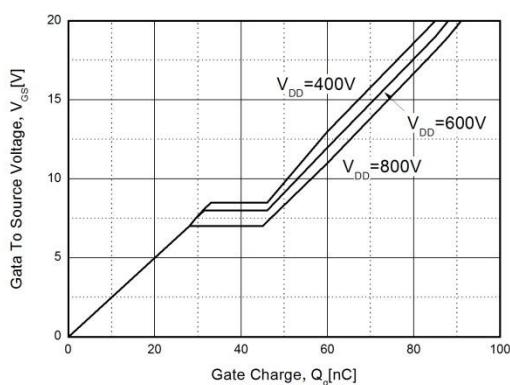


Fig. 8. Characteristics vs. Drain-to-Source Voltage

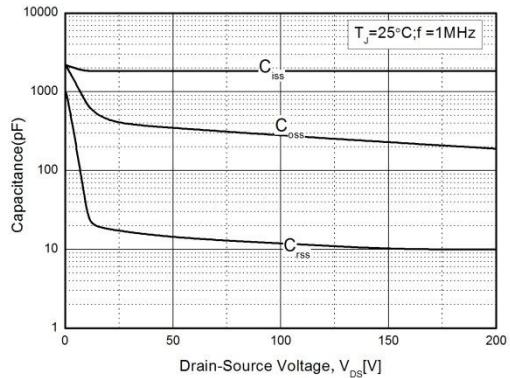
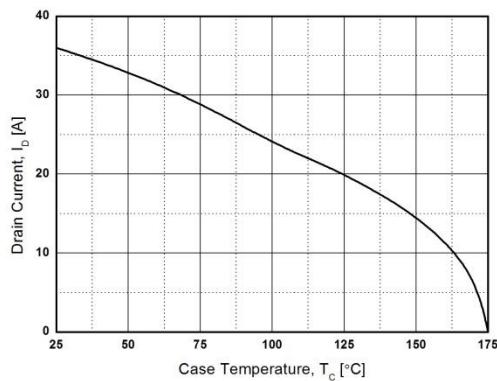


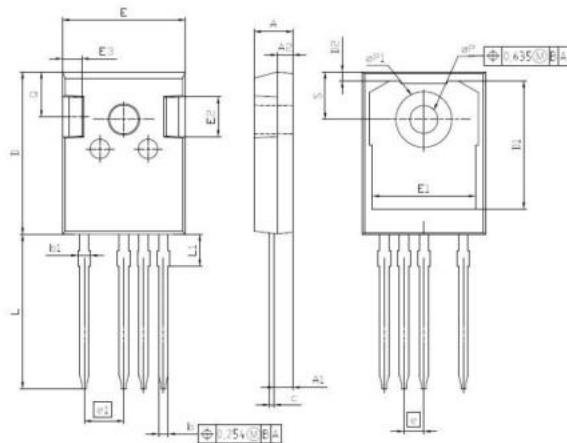
Fig. 9. Maximum Drain Current vs. Temperature



## Package Dimensions

**TO-247-4L**

(Dimensions in Millimeters)



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.90	2.16	0.075	0.085
b	1.07	1.33	0.042	0.052
b1	1.10	1.70	0.043	0.067
c	0.50	0.70	0.020	0.028
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	2.54 (BSC)		0.100 (BSC)	
e1	5.08		0.200	
N	4		4	
L	19.72	20.32	0.776	0.800
L1	4.02	4.40	0.158	0.173
øP	3.50	3.70	0.138	0.146
øP1	7.00	7.40	0.276	0.291
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248